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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Discontinued at Digi-Key
Core Processor	CIP-51 8051
Core Size	8-Bit
Speed	50MHz
Connectivity	I ² C, SMBus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	29
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2.25K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 20x10/12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-UFQFN Exposed Pad
Supplier Device Package	32-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm8bb31f32g-a-qfn32r

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

2. Ordering Information

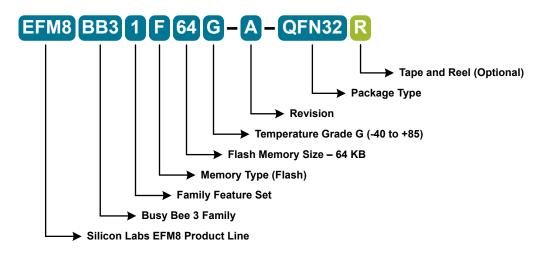


Figure 2.1. EFM8BB3 Part Numbering

All EFM8BB3 family members have the following features:

- · CIP-51 Core running up to 49 MHz
- Three Internal Oscillators (49 MHz, 24.5 MHz and 80 kHz)
- SMBus
- I2C Slave
- SPI
- 2 UARTs
- · 6-Channel Programmable Counter Array (PWM, Clock Generation, Capture/Compare)
- · Six 16-bit Timers
- Four Configurable Logic Units
- 12-bit Analog-to-Digital Converter with integrated multiplexer, voltage reference, temperature sensor, channel sequencer, and directto-XRAM data transfer
- Two Voltage Digital-to-Analog Converters (DACs)
- Two Analog Comparators
- 16-bit CRC Unit
- · AEC-Q100 qualified (pending)

In addition to these features, each part number in the EFM8BB3 family has a set of features that vary across the product line. The product selection guide shows the features available on each family member.

Table 2.1.	Product Selection Guide	

Ordering Part Number	Flash Memory (kB)	RAM (Bytes)	Digital Port I/Os (Total)	Number of DACs	ADC0 Channels	Comparator 0 Inputs	Comparator 1 Inputs	Pb-free (RoHS Compliant)	Temperature Range	Package
EFM8BB31F64G-A-QFN32	64	4352	29	4	20	10	9	Yes	-40 to +85 °C	QFN32
EFM8BB31F64G-A-QFP32	64	4352	28	4	20	10	9	Yes	-40 to +85 °C	QFP32
EFM8BB31F64G-A-QFN24	64	4352	20	4	12	6	6	Yes	-40 to +85 °C	QFN24

3.2 Power

All internal circuitry draws power from the VDD supply pin. External I/O pins are powered from the VIO supply voltage (or VDD on devices without a separate VIO connection), while most of the internal circuitry is supplied by an on-chip LDO regulator. Control over the device power can be achieved by enabling/disabling individual peripherals as needed. Each analog peripheral can be disabled when not in use and placed in low power mode. Digital peripherals, such as timers and serial buses, have their clocks gated off and draw little power when they are not in use.

Table 3.1. Power Modes

Power Mode	Details	Mode Entry	Wake-Up Sources
Normal	Core and all peripherals clocked and fully operational		
ldle	 Core halted All peripherals clocked and fully operational Code resumes execution on wake event 	Set IDLE bit in PCON0	Any interrupt
Suspend	 Core and peripheral clocks halted HFOSC0 and HFOSC1 oscillators stopped Regulator in normal bias mode for fast wake Timer 3 and 4 may clock from LFOSC0 Code resumes execution on wake event 	 Switch SYSCLK to HFOSC0 Set SUSPEND bit in PCON1 	 Timer 4 Event SPI0 Activity I2C0 Slave Activity Port Match Event Comparator 0 Rising Edge CLUn Interrupt-Enabled Event
Stop	 All internal power nets shut down Pins retain state Exit on any reset source 	1. Clear STOPCF bit in REG0CN 2. Set STOP bit in PCON0	Any reset source
Snooze	 Core and peripheral clocks halted HFOSC0 and HFOSC1 oscillators stopped Regulator in low bias current mode for energy savings Timer 3 and 4 may clock from LFOSC0 Code resumes execution on wake event 	 Switch SYSCLK to HFOSC0 Set SNOOZE bit in PCON1 	 Timer 4 Event SPI0 Activity I2C0 Slave Activity Port Match Event Comparator 0 Rising Edge CLUn Interrupt-Enabled Event
Shutdown	 All internal power nets shut down Pins retain state Exit on pin or power-on reset 	1. Set STOPCF bit in REG0CN 2. Set STOP bit in PCON0	RSTb pin resetPower-on reset

3.3 I/O

Digital and analog resources are externally available on the device's multi-purpose I/O pins. Port pins P0.0-P2.3 can be defined as general-purpose I/O (GPIO), assigned to one of the internal digital resources through the crossbar or dedicated channels, or assigned to an analog function. Port pins P2.4 to P3.7 can be used as GPIO. Additionally, the C2 Interface Data signal (C2D) is shared with P3.0 or P3.7, depending on the package option.

The port control block offers the following features:

- Up to 29 multi-functions I/O pins, supporting digital and analog functions.
- · Flexible priority crossbar decoder for digital peripheral assignment.
- Two drive strength settings for each port.
- State retention feature allows pins to retain configuration through most reset sources.
- Two direct-pin interrupt sources with dedicated interrupt vectors (INT0 and INT1).
- Up to 24 direct-pin interrupt sources with shared interrupt vector (Port Match).

Timers (Timer 0, Timer 1, Timer 2, Timer 3, Timer 4, and Timer 5)

Several counter/timers are included in the device: two are 16-bit counter/timers compatible with those found in the standard 8051, and the rest are 16-bit auto-reload timers for timing peripherals or for general purpose use. These timers can be used to measure time intervals, count external events and generate periodic interrupt requests. Timer 0 and Timer 1 are nearly identical and have four primary modes of operation. The other timers offer both 16-bit and split 8-bit timer functionality with auto-reload and capture capabilities.

Timer 0 and Timer 1 include the following features:

- Standard 8051 timers, supporting backwards-compatibility with firmware and hardware.
- Clock sources include SYSCLK, SYSCLK divided by 12, 4, or 48, the External Clock divided by 8, or an external pin.
- · 8-bit auto-reload counter/timer mode
- 13-bit counter/timer mode
- 16-bit counter/timer mode
- Dual 8-bit counter/timer mode (Timer 0)

Timer 2, Timer 3, Timer 4, and Timer 5 are 16-bit timers including the following features:

- · Clock sources for all timers include SYSCLK, SYSCLK divided by 12, or the External Clock divided by 8
- · LFOSC0 divided by 8 may be used to clock Timer 3 and Timer 4 in active or suspend/snooze power modes
- Timer 4 is a low-power wake source, and can be chained together with Timer 3
- 16-bit auto-reload timer mode
- Dual 8-bit auto-reload timer mode
- · External pin capture
- · LFOSC0 capture
- Comparator 0 capture
- Configurable Logic output capture

Watchdog Timer (WDT0)

The device includes a programmable watchdog timer (WDT) running off the low-frequency oscillator. A WDT overflow forces the MCU into the reset state. To prevent the reset, the WDT must be restarted by application software before overflow. If the system experiences a software or hardware malfunction preventing the software from restarting the WDT, the WDT overflows and causes a reset. Following a reset, the WDT is automatically enabled and running with the default maximum time interval. If needed, the WDT can be disabled by system software or locked on to prevent accidental disabling. Once locked, the WDT cannot be disabled until the next system reset. The state of the RST pin is unaffected by this reset.

The Watchdog Timer has the following features:

- · Programmable timeout interval
- · Runs from the low-frequency oscillator
- · Lock-out feature to prevent any modification until a system reset

3.6 Communications and Other Digital Peripherals

Universal Asynchronous Receiver/Transmitter (UART0)

UART0 is an asynchronous, full duplex serial port offering modes 1 and 3 of the standard 8051 UART. Enhanced baud rate support allows a wide range of clock sources to generate standard baud rates. Received data buffering allows UART0 to start reception of a second incoming data byte before software has finished reading the previous data byte.

The UART module provides the following features:

- · Asynchronous transmissions and receptions
- Baud rates up to SYSCLK/2 (transmit) or SYSCLK/8 (receive)
- 8- or 9-bit data
- · Automatic start and stop generation
- · Single-byte buffer on transmit and receive

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
Offset Temperature Coefficient	TC _{OFF}		—	TBD	_	LSB/°C
Slope Error	E _M	12 Bit Mode	_	TBD	TBD	%
		10 Bit Mode	—	TBD	—	%
Dynamic Performance 10 kHz Sine	Wave Input	1 dB below full scale, Max throughput	t, using AGN	D pin		
Signal-to-Noise	SNR	12 Bit Mode	_	TBD	_	dB
		10 Bit Mode	—	TBD	_	dB
Signal-to-Noise Plus Distortion	SNDR	12 Bit Mode	TBD	TBD	_	dB
		10 Bit Mode	_	TBD	_	dB
Total Harmonic Distortion (Up to	THD	12 Bit Mode	—	TBD	_	dB
5th Harmonic)		10 Bit Mode	_	TBD	_	dB
Spurious-Free Dynamic Range	SFDR	12 Bit Mode	_	TBD	_	dB
		10 Bit Mode	_	TBD	_	dB

Note:

1. Conversion Time does not include Tracking Time. Total Conversion Time is:

Total Conversion Time = [RPT × (ADTK + NUMBITS + 1) × T(SARCLK)] + (T(ADCCLK) × 4)

where RPT is the number of conversions represented by the ADRPT field and ADCCLK is the clock selected for the ADC.

2. Absolute input pin voltage is limited by the V_{IO} supply.

5. Typical Connection Diagrams

5.1 Power

Figure 5.1 Power Connection Diagram on page 28 shows a typical connection diagram for the power pins of the device.

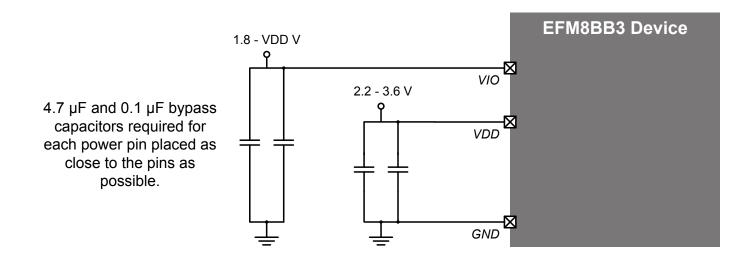


Figure 5.1. Power Connection Diagram

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
15	P2.2	Multifunction I/O	Yes	P2MAT.2	ADC0.15
				CLU2OUT	CMP1P.4
				CLU1A.15	CMP1N.4
				CLU2B.14	
				CLU3A.14	
16	P2.1	Multifunction I/O	Yes	P2MAT.1	ADC0.14
				I2C0_SCL	CMP1P.3
				CLU1B.14	CMP1N.3
				CLU2A.15	
				CLU3B.15	
17	P2.0	Multifunction I/O	Yes	P2MAT.0	CMP1P.2
				I2C0_SDA	CMP1N.2
				CLU1A.14	
				CLU2A.14	
				CLU3B.14	
18	P1.7	Multifunction I/O	Yes	P1MAT.7	ADC0.13
				CLU0B.15	CMP0P.9
				CLU1B.13	CMP0N.9
				CLU2A.13	
19	P1.6	Multifunction I/O	Yes	P1MAT.6	ADC0.12
				CLU0A.15	
				CLU1B.12	
				CLU2A.12	
20	P1.5	Multifunction I/O	Yes	P1MAT.5	ADC0.11
				CLU0B.14	
				CLU1A.13	
				CLU2B.13	
				CLU3B.11	
21	P1.4	Multifunction I/O	Yes	P1MAT.4	ADC0.10
				CLU0A.14	
				CLU1A.12	
				CLU2B.12	
				CLU3B.10	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
22	P1.3	Multifunction I/O	Yes	P1MAT.3	ADC0.9
				CLU0B.13	
				CLU1B.11	
				CLU2B.11	
				CLU3A.13	
23	P1.2	Multifunction I/O	Yes	P1MAT.2	ADC0.8
				CLU0A.13	CMP0P.8
				CLU1A.11	CMP0N.8
				CLU2B.10	
				CLU3A.12	
				CLU3B.13	
24	P1.1	Multifunction I/O	Yes	P1MAT.1	ADC0.7
				CLU0B.12	CMP0P.7
				CLU1B.10	CMP0N.7
				CLU2A.11	
				CLU3B.12	
25	P1.0	Multifunction I/O	Yes	P1MAT.0	ADC0.6
				CLU1OUT	CMP0P.6
				CLU0A.12	CMP0N.6
				CLU1A.10	CMP1P.1
				CLU2A.10	CMP1N.1
26	P0.7	Multifunction I/O	Yes	P0MAT.7	ADC0.5
				INT0.7	CMP0P.5
				INT1.7	CMP0N.5
				CLU0B.11	CMP1P.0
				CLU1B.9	CMP1N.0
				CLU3A.11	
27	P0.6	Multifunction I/O	Yes	P0MAT.6	ADC0.4
				CNVSTR	CMP0P.4
				INT0.6	CMP0N.4
				INT1.6	
				CLU0A.11	
				CLU1B.8	
				CLU3A.10	

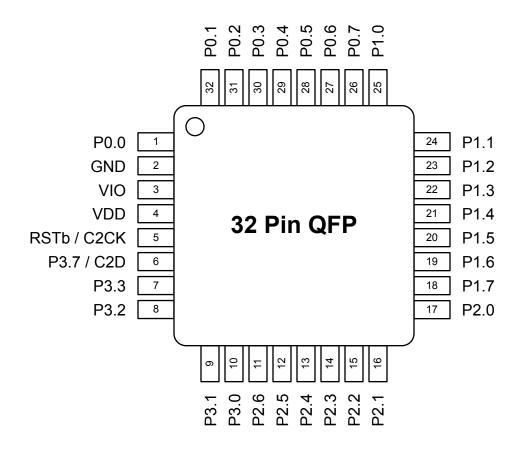


Figure 6.2. EFM8BB3x-QFP32 Pinout

Table 6.2.	Pin Definitions	for EFM8BB3x-QFP32
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Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
1	P0.0	Multifunction I/O	Yes	P0MAT.0	VREF
				INT0.0	
				INT1.0	
				CLU0A.8	
				CLU2A.8	
				CLU3B.8	
2	GND	Ground			
3	VIO	I/O Supply Power Input			
4	VDD	Supply Power Input			
5	RSTb /	Active-low Reset /			
	C2CK	C2 Debug Clock			

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
25	P1.0	Multifunction I/O	Yes	P1MAT.0	ADC0.6
				CLU1OUT	CMP0P.6
				CLU0A.12	CMP0N.6
				CLU1A.10	CMP1P.1
				CLU2A.10	CMP1N.1
26	P0.7	Multifunction I/O	Yes	POMAT.7	ADC0.5
				INT0.7	CMP0P.5
				INT1.7	CMP0N.5
				CLU0B.11	CMP1P.0
				CLU1B.9	CMP1N.0
				CLU3A.11	
27	P0.6	Multifunction I/O	Yes	P0MAT.6	ADC0.4
				CNVSTR	CMP0P.4
				INT0.6	CMP0N.4
				INT1.6	
				CLU0A.11	
				CLU1B.8	
				CLU3A.10	
28	P0.5	Multifunction I/O	Yes	P0MAT.5	ADC0.3
				INT0.5	CMP0P.3
				INT1.5	CMP0N.3
				UART0_RX	
				CLU0B.10	
				CLU1A.9	
29	P0.4	Multifunction I/O	Yes	P0MAT.4	ADC0.2
				INT0.4	CMP0P.2
				INT1.4	CMP0N.2
				UART0_TX	
				CLU0A.10	
				CLU1A.8	

6.3 EFM8BB3x-QFN24 Pin Definitions

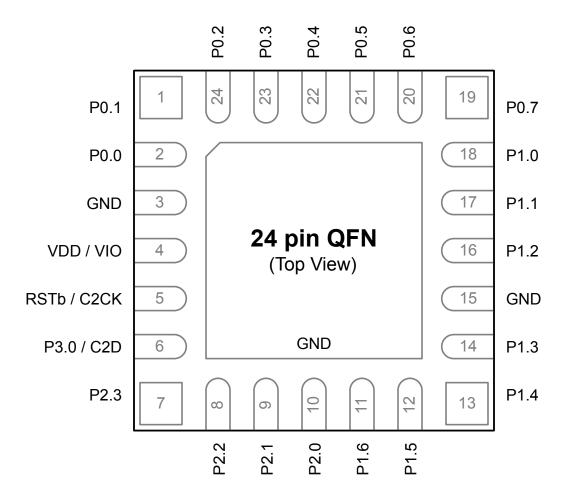




Table 6.3. Pin Definitions for EFM8BB3x-QFN24

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
1	P0.1	Multifunction I/O	Yes	P0MAT.1	ADC0.0
				INT0.1	CMP0P.0
				INT1.1	CMP0N.0
				CLU0B.8	AGND
				CLU2A.9	
				CLU3B.9	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
2	P0.0	Multifunction I/O	Yes	P0MAT.0	VREF
				INT0.0	
				INT1.0	
				CLU0A.8	
				CLU2A.8	
				CLU3B.8	
3	GND	Ground			
4	VDD / VIO	Supply Power Input			
5	RSTb /	Active-low Reset /			
	C2CK	C2 Debug Clock			
6	P3.0 /	Multifunction I/O /			
	C2D	C2 Debug Data			
7	P2.3	Multifunction I/O	Yes	P2MAT.3	DAC3
				CLU1B.15	
				CLU2B.15	
				CLU3A.15	
8	P2.2	Multifunction I/O	Yes	P2MAT.2	DAC2
				CLU1A.15	
				CLU2B.14	
				CLU3A.14	
9	P2.1	Multifunction I/O	Yes	P2MAT.1	DAC1
				CLU1B.14	
				CLU2A.15	
				CLU3B.15	
10	P2.0	Multifunction I/O	Yes	P2MAT.0	DAC0
				CLU1A.14	
				CLU2A.14	
				CLU3B.14	
11	P1.6	Multifunction I/O	Yes	P1MAT.6	ADC0.11
				CLU3OUT	CMP1P.5
				CLU0A.15	CMP1N.5
				CLU1B.12	
				CLU2A.12	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
24	P0.2	Multifunction I/O	Yes	P0MAT.2	XTAL1
				INT0.2	ADC0.1
				INT1.2	CMP0P.1
				CLU0OUT	CMP0N.1
				CLU0A.9	
				CLU2B.8	
				CLU3A.8	
Center	GND	Ground			

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
2	P0.2	Multifunction I/O	Yes	P0MAT.2	XTAL1
				INT0.2	ADC0.1
				INT1.2	CMP0P.1
				CLU0OUT	CMP0N.1
				CLU0A.9	
				CLU2B.8	
				CLU3A.8	
3	P0.1	Multifunction I/O	Yes	P0MAT.1	ADC0.0
				INT0.1	CMP0P.0
				INT1.1	CMP0N.0
				CLU0B.8	AGND
				CLU2A.9	
				CLU3B.9	
4	P0.0	Multifunction I/O	Yes	P0MAT.0	VREF
				INT0.0	
				INT1.0	
				CLU0A.8	
				CLU2A.8	
				CLU3B.8	
5	GND	Ground			
6	VDD / VIO	Supply Power Input			
7	RSTb /	Active-low Reset /			
	C2CK	C2 Debug Clock			
8	P3.0 /	Multifunction I/O /			
	C2D	C2 Debug Data			
9	P2.3	Multifunction I/O	Yes	P2MAT.3	DAC3
				CLU1B.15	
				CLU2B.15	
				CLU3A.15	
10	P2.2	Multifunction I/O	Yes	P2MAT.2	DAC2
				CLU1A.15	
				CLU2B.14	
				CLU3A.14	

8.2 QFP32 PCB Land Pattern

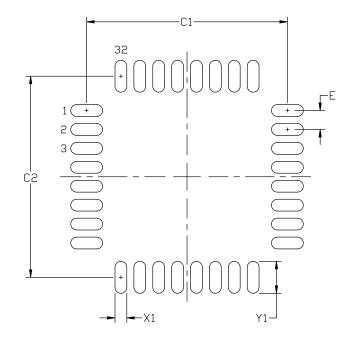


Figure 8.2. QFP32 PCB Land Pattern Drawing

Table 8.2.	QFP32 PCB La	and Pattern	Dimensions
------------	--------------	-------------	------------

Dimension	Min Max								
C1	8.40	8.50							
C2	8.40	8.50							
E	0.80 BSC								
X1	0.55								
Y1	1.5								

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.

2. This Land Pattern Design is based on the IPC-7351 guidelines.

3. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

4. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.

5. The stencil thickness should be 0.125 mm (5 mils).

6. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.

7. A No-Clean, Type-3 solder paste is recommended.

8. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

9. QFN24 Package Specifications

9.1 QFN24 Package Dimensions

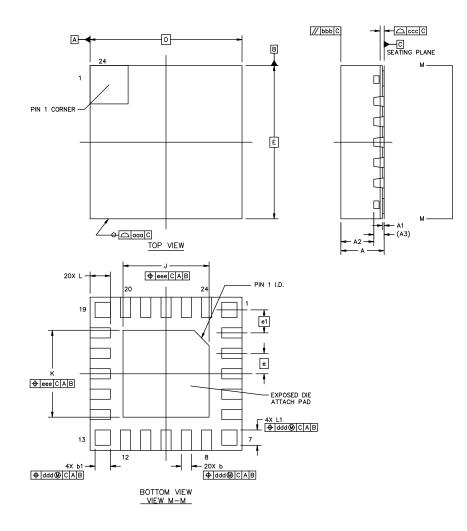


Figure 9.1. QFN24 Package Drawing

Table 9.1.	QFN24 Package Dimensions
------------	--------------------------

Dimension	Min	Тур	Мах						
A	0.8	0.85	0.9						
A1	0.00	_	0.05						
A2	—	0.65	—						
A3		0.203 REF							
b	0.15	0.2	0.25						
b1	0.25	0.3	0.35						
D	3.00 BSC								
E	3.00 BSC								

10. QSOP24 Package Specifications

10.1 QSOP24 Package Dimensions

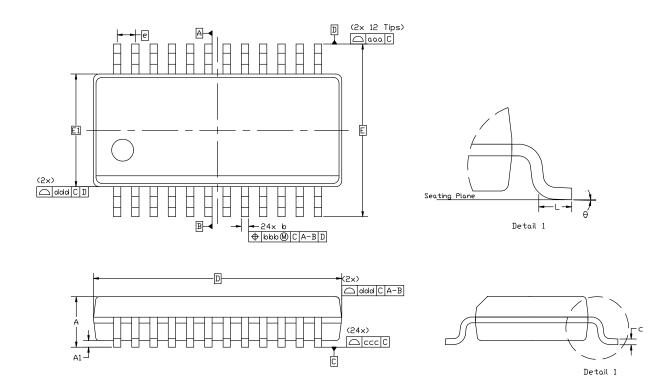


Figure 10.1. QSOP24 Package Drawing

Table 10.1. QSOP24 Package Dimensions

Dimension	Min	Тур	Мах					
A	—	—	1.75					
A1	0.10	—	0.25					
b	0.20	_	0.30					
С	0.10	_	0.25					
D	8.65 BSC							
E	6.00 BSC							
E1	3.90 BSC							
е	0.635 BSC							
L	0.40	_	1.27					
theta	0°	—	8°					

Dimension	Min	Тур	Мах					
ааа		0.20						
bbb		0.18						
ссс		0.10						
ddd		0.10						

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.

2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

3. This drawing conforms to JEDEC outline MO-137, variation AE.

4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

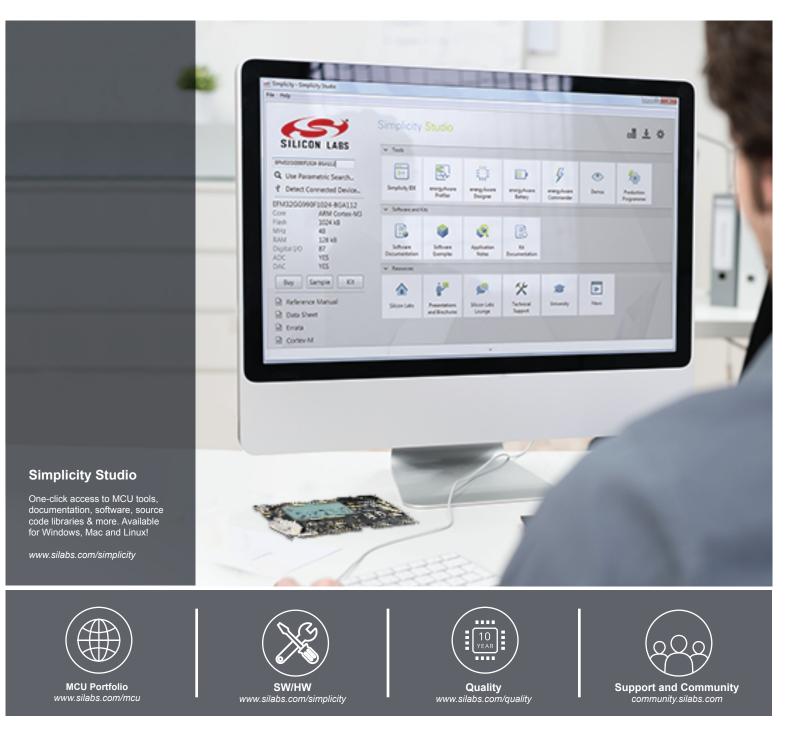


Figure 10.3. QSOP24 Package Marking

The package marking consists of:

- PPPPPPP The part number designation.
- TTTTTT A trace or manufacturing code.
- YY The last 2 digits of the assembly year.
- WW The 2-digit workweek when the device was assembled.
- # The device revision (A, B, etc.).

	6.3 EFM8BB3x-QFN24 Pin Definitions									.40
	6.4 EFM8BB3x-QSOP24 Pin Definitions									.45
7.	QFN32 Package Specifications.									50
	7.1 QFN32 Package Dimensions									.50
	7.2 QFN32 PCB Land Pattern									.52
	7.3 QFN32 Package Marking									.53
8.	QFP32 Package Specifications.									54
	8.1 QFP32 Package Dimensions									.54
	8.2 QFP32 PCB Land Pattern									.56
	8.3 QFP32 Package Marking									.57
9.	QFN24 Package Specifications.									58
	9.1 QFN24 Package Dimensions									.58
	9.2 QFN24 PCB Land Pattern									.60
	9.3 QFN24 Package Marking									.61
10.). QSOP24 Package Specifications									62
	10.1 QSOP24 Package Dimensions									.62
	10.2 QSOP24 PCB Land Pattern									.64
	10.3 QSOP24 Package Marking									.65
11.	I.Revision History.									66
	11.1 Revision 0.1									.66
	11.2 Revision 0.2									.66
Tab	able of Contents									67



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